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Jameco Part Number 1976831

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| В | 4. THIS PRODUCT NOT INTENDED FOR LEAD FREE, (RoHS), REFLOW PROCESS. REFLOW TEMPERATURE SHOULD NOT EXCEED 180°C | NO GENERAL TOLERANCES DMENSON STYLE SCALE DESIGN UNITS Image: Third Constraints NO SYMBOLS (UNLESS SPECFIED) ORAWN BY DATE THE METRIC Image: Constraints Image: Constra | B |
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| в | 4. THIS PRODUCT NOT INTENDED FOR LEAD FREE, REFLOW PROCESS. REFLOW TEMPERATURE SHOULD NOT EXCEED 180°C. FOR REFLOW PROCESSES GREATER THAN 180°C, REFER TO MOLEX | | Image: Second secon | в |
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